### Combinational Logic Gates in CMOS

References:

Adapted from*: Digital Integrated Circuits: A Design Perspective*, J. Rabaey, Prentice Hall © UCB *Principles of CMOS VLSI Design: A Systems Perspective*, N. H. E. Weste, K. Eshraghian, Addison Wesley Adapted from: EE216A Lecture Notes by Prof. K. Bult © UCLA

#### Combinational vs. Sequential Logic



 $Out = f(ln)$  Out =  $f(ln, State)$ 

State is related to previous inputs Stored in registers, memory etc

## **Overview**

- Static CMOS
	- Complementary CMOS
	- Ratioed Logic
	- Pass Transistor/Transmission Gate Logic
- Dynamic CMOS Logic
	- Domino
	- np-CMOS

## Static CMOS Circuit

- At every point in time (except during the switching transients) each gate output is connected to either  $\rm V_{\scriptscriptstyle \rm DD}$  or  $\rm V_{\scriptscriptstyle SS}$  via a low-resistive path
- The outputs of the gates assume at all times the value of the Boolean function, implemented by the circuit
- In contrast, a dynamic circuit relies on temporary storage of signal values on the capacitance of high impedance circuit nodes

## Digital Gates Fundamental Parameters

- Area and Complexity
- Performance
- Power Consumption
- Robustness and Reliability

## What Can Go Wrong in CMOS Logic?

- $\bullet$ Incorrect or insufficient power supplies
- •Power supply noise + Complementary CMOS is pretty
- • Noise on gate input safe against these
- •Faulty connections between transistors
- Clock frequency too high or circuit too slow

## How about Ratioed or Dynamic Logic?

- All the previous and
- $\bullet$ Incorrect ratios in ratioed logic
- Charge sharing in dynamic logic
- $\bullet$ Incorrect clocking in dynamic logic

#### Complementary CMOS



PUN and PDN are dual networks

NMOS Transistors in Series/Parallel Connection

- Transistors can be thought as a switch controlled by its gate signal
- NMOS switch closes when switch control input is high



•NMOS passes a strong 0 but a weak 1

#### NMOS Transistors in Series/Parallel Connection

•Connect Y to GND



•Implement the complement of PDN PMOS Transistors in Series/Parallel Connection

• PMOS switch closes when switch control input is low



• PMOS passes a strong 1 but a weak 0

### PMOS Transistors in Series/Parallel Connection

•Connect Y to VDD



• Combine series PDN and parallel PUN or parallel PDN and series PUN to complete the logic design to output good 1 and 0

Complementary CMOS Logic Style Construction

• PUN is the DUAL of PDN (can be shown using DeMorgan's Theorems)

$$
\overline{A+B} = \overline{A}\overline{B}
$$

$$
\overline{AB} = \overline{A} + \overline{B}
$$

$$
G(in_1, in_2, in_3, \ldots) \equiv F(in_1, in_2, in_3, \ldots)
$$

- The complementary gate is inverting
	- Implements NAND, NOR, …
	- Non-inverting boolean function needs an inverter



### The NAND Circuit



 $G(in_1, in_2, in_3, ...) \equiv F(in_1, in_2, in_3, ...)$ PDN connected to GND :*G* <sup>=</sup> *A*.*B* PUN connected to  $V_{DD}: F = A+B = AB$ 

## The NOR Circuit



## Example Gate: COMPLEX CMOS GATE



$$
F = ((A.B) + C.(A+B)) = carry
$$



Symmetrical !



#### Full Adder Circuit



#### 4-input NAND Gate



**In1 In2 In3 In4**

#### Standard Cell Layout Methodology



Two Versions of (a+b).c



## Logic Graph



#### Consistent Euler Path



#### Example:  $x = ab + cd$



## Properties of Complementary CMOS Gates

- High noise margin
	- $\rm V_{OH}$  and  $\rm V_{OL}$  are at  $\rm V_{DD}$  and  $\rm G_{ND}$ , respectively
- No static power consumption
	- In steady state, no direct path between  $\mathsf{V}_{\texttt{DD}}$  and  $\mathsf{V}_{\texttt{SS}}$
- Comparable rise and fall times under appropriate scaling of PMOS and NMOS transistors

## Transistor Sizing



- •For symmetrical response (dc, ac)
- •For performance
- •Input dependent
- •Focus on worst-case

#### Propagation Delay Analysis - The Switch Model

 $V_{DD}$  $R_p$  $\overline{A}$  $\mathcal F$  $R_{n}$  $C_L$  $\boldsymbol{A}$ 

 $V_{DD}$  $R_{\rho}$  $R_p$  $\overline{\mathsf{A}}$  $\overline{B}$ F  $R_{n}$  $C_L$  $B^{\circ}$  $R_{n}$ Α



(a) Inverter

(b) Two-input NAND

(c) Two-input NOR

#### Analysis of Propagation Delay



(b) Two-input NAND

- •Assume C<sub>L</sub> dominates
- Assume  $R_n = R_p =$  resistance of minimum sized NMOS inverter
	- For  $t_{\text{plH}}$

•

 Worst case when only one PMOS pulls up the output node

$$
- t_{pLH} \propto R_p C_L
$$

- •For  $t_{pHL}$ 
	- Worst case when two NMOS in series

 $-$  t<sub>pHL</sub>  $\propto$  2R<sub>n</sub>C<sub>L</sub>

#### 3-Input NAND Gate



#### 3-Input NAND Gate



Take 
$$
W_n = (3/2)W_p
$$

## Design for Worst Case



#### 3-input NAND Gate with Parasitic Capacitors



#### Worst Case Approximation Using Lumped RC Model

 $(R_{N1} + R_{N2} + R_{N3}) \times (C_a + C_b + (C_c + C_{p+load}))$  $df$  *pulldown*  $\sim$  *pulldown*  $P = (R_{N1} + R_{N2} + R_{N3}) \times (C_a + C_b + (C_c + C_{p+1})$  $t_{\textit{df}} = \sum R_{\textit{pulldown}} \times \sum C$ (We ignore the constant term 0.69 or 1.22)

### Penfield-Rubenstein Model (Elmore Delay Model)

$$
t_d = \sum R_i C_i
$$
  
with:  $C_i$  = capacitance at node i  
 $R_i$  = total resistance between  $C_i$  and supply

$$
t_{df} = [R_{N1}C_a] + [(R_{N1} + R_{N2})C_b] +
$$

$$
[(R_{N1} + R_{N2} + R_{N3})(C_c + C_{p+load})]
$$

#### Distributed RC Effects



## **Comparison**

#### RP-Model



#### Macro Modeling



$$
\left| \begin{array}{c} t_d = T_{d,\text{ internal}} + \lambda \times C_{\text{load}} \end{array} \right|
$$

### Effect of Loading



# Effect of Fan-In and Fan-Out on Delay

$$
t_d = a_1 FI + a_2 FI^2 + a_3 FO
$$

- Fan-out: number of gates connected
	- 2 gate capacitance per fan-out
- $\bullet$  Fan-in: number of inputs to a gate
	- Quadratic effect due to increasing resistance and capacitance



# *t*<sub>p</sub> as a function of Fan-In



*AVOID LARGE FAN-IN GATES! (Typically not more than FI < 4)*

## Example 3-Input NAND gate with Parasitic Capacitors



#### Worst Case Approximation by Lumped Model

 $\rm t_{dr}$  =  $\rm R_p$  x (C $_{\rm c}$  + C $_{\rm p+load}$ ) = 10000 x 0.4 $\times$ 10<sup>-12</sup> = 4.0ns  $\bm{{\mathsf{t}}}_{\mathsf{df}} = \Sigma \bm{\mathsf{R}}_{\mathsf{pulldown}}$  x  $\Sigma \bm{\mathsf{C}}_{\mathsf{pulldown}}$  $=(R_{N1}+R_{N2}+R_{N3})\times (C_a+C_b+(C_c+C_{p+load}))$  $= (3 \times 5000) \times (3 \times 0.05 + 0.15 + 0.20) \times 10^{-12}$  $= 7.5$ ns

#### Penfield-Rubenstein Model

$$
t_{dr} = R_p \times (C_c + C_{p+load}) = 10000 \times 0.4 \times 10^{-12} = 4.0
$$
ns  
\n $t_{dr} = [R_{N1}C_a] + [(R_{N1} + R_{N2})C_b] + [(R_{N1} + R_{N2} + R_{N3})(C_c + C_{p+load})]$   
\n $= 5000 \times 0.05pF + 10000 \times 0.05pF + 15000 \times 0.4pF = 6.75$ ns

#### Worst Case Approximation by Lumped Model

Make  $\,$  W $_{\textrm{n}}$  = 2W $_{\textrm{p}}$ 

 $\rm t_{dr}$  =  $\rm R_p$  x (C $_{\rm c}$  + C $_{\rm p+load}$ ) = 10000 x 0.45 $\times$ 10<sup>-12</sup> = 4.5ns

$$
t_{df} = \Sigma R_{\text{pulldown}} \times \Sigma C_{\text{pulldown}}
$$

 $=(R_{N1}+R_{N2}+R_{N3})\times (C_a+C_b+(C_c+C_{p+load}))$  $= (3 \times 2500) \times (3 \times 0.10 + 0.15 + 0.20) \times 10^{-12}$ = 4.875ns

### Penfield-Rubenstein Model

Make 
$$
W_n = 2W_p
$$
  
\n $t_{dr} = R_p \times (C_c + C_{p+load}) = 10000 \times 0.45 \times 10^{-12} = 4.5 \text{ns}$   
\n $t_{dr} = [R_{N1}C_a] + [(R_{N1} + R_{N2})C_b] + [(R_{N1} + R_{N2} + R_{N3})(C_c + C_{p+load})]$   
\n $= 2500 \times 0.10pF + 5000 \times 0.10pF + 7500 \times 0.45pF = 4.125 \text{ns}$ 

#### Rewriting Penfield-Rubenstein Equation

$$
t_{d} = [R_{N1}C_{a}] + [(R_{N1} + R_{N2})C_{b}] +
$$
  
\n
$$
[(R_{N1} + R_{N2} + R_{N3})(C_{c} + C_{p+load})]
$$
  
\n
$$
\implies t_{d} = [R_{N1}(C_{a} + C_{b} + C_{c} + C_{p+load})] +
$$
  
\n
$$
[R_{N2}(C_{b} + C_{c} + C_{p+load})] +
$$
  
\n
$$
[R_{N3}(C_{c} + C_{p+load})]
$$

 $\boldsymbol{\mathsf{t}}_\mathsf{d} = \Sigma \; \boldsymbol{\mathsf{R}}_\mathsf{ii} \boldsymbol{\mathsf{C}}_\mathsf{downstream}$ -i

with:  $C_{downstream-i} = downstream$  capacitance at node i  $\mathsf{R}_{\boldsymbol{\mathfrak{ij}}}$  = resistance at node i

### Progressive Sizing

- When parasitic capacitance is significant (e.g., when fanin is large), needs to consider distributed RC effect
- Increasing the size of M1 has the largest impact in terms of delay reduction
- $\bullet~~ \mathsf{M}_1 > \mathsf{M}_2 > \mathsf{M}_3 > \ldots > \mathsf{M}_\mathsf{N}$



### Delay Optimization by Transistor Ordering



Critical signal next to supply



Critical signal next to output